

SN74CBTD16211 24-BIT FET BUS SWITCH WITH LEVEL SHIFTING

SCDS048H – MARCH 1998 – REVISED JULY 2002

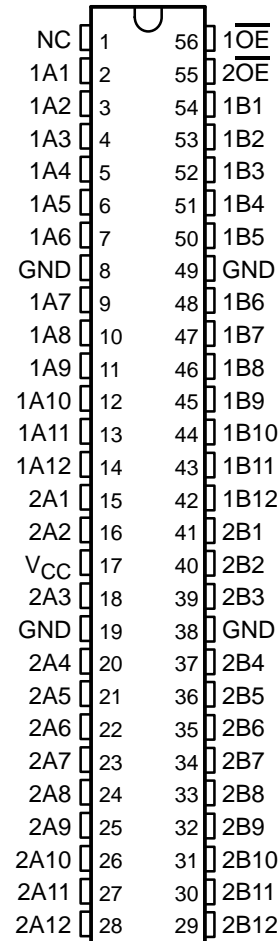
- Member of Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications

description/ordering information

The SN74CBTD16211 provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to V_{CC} is integrated in the circuit to allow for level shifting from 5-V signals at the device inputs to 3.3-V signals at the device outputs.

The device is organized as a dual 12-bit bus switch with separate output-enable (\overline{OE}) inputs. It can be used as two 12-bit bus switches or as one 24-bit bus switch. When \overline{OE} is low, the associated 12-bit bus switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the ports.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74CBTD16211DL	CBTD16211
		Tape and reel	SN74CBTD16211DLR	
	TSSOP – DGG	Tape and reel	SN74CBTD16211DGGR	CBTD16211
	TVSOP – DGV	Tape and reel	SN74CBTD16211DGVR	CYD211

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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24-BIT FET BUS SWITCH

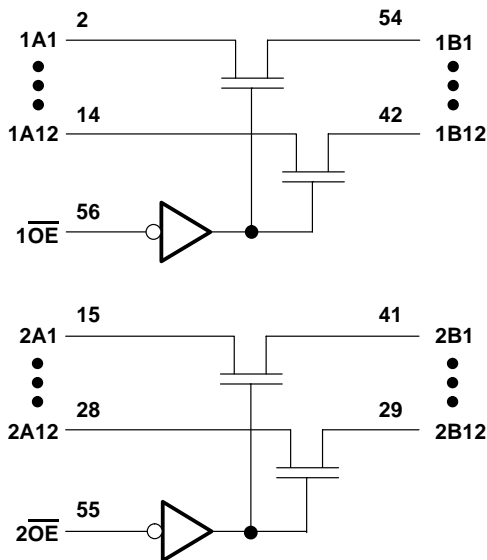
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FUNCTION TABLE
(each 12-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	64°C/W
DGV package	48°C/W
DL package	56°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



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SCDS048H – MARCH 1998 – REVISED JULY 2002

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4.5	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	-40	85	°C

In applications with fast edge rates, multiple outputs switching, and operating at high frequencies, the output may have little or no level-shifting effect.

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
V _{OH}	See Figure 2					
I _I	V _{CC} = 5.5 V,	V _I = 5.5 V or GND			±1	μA
I _{CC}	V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND			1.5	mA
ΔI _{CC} ‡	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs	V _I = 3 V or 0		3		pF
C _{io(OFF)}	V _O = 3 V or 0,	\overline{OE} = V _{CC}		5.5		pF
r _{on} §	V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA	5	7	Ω
			I _I = 30 mA	5	7	
		V _I = 2.4 V,	I _I = 15 mA	35	50	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} ¶	A or B	B or A		0.25	ns
t _{en}	\overline{OE}	A or B	1.5	9.8	ns
t _{dis}	\overline{OE}	A or B	1.5	8.9	ns

¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



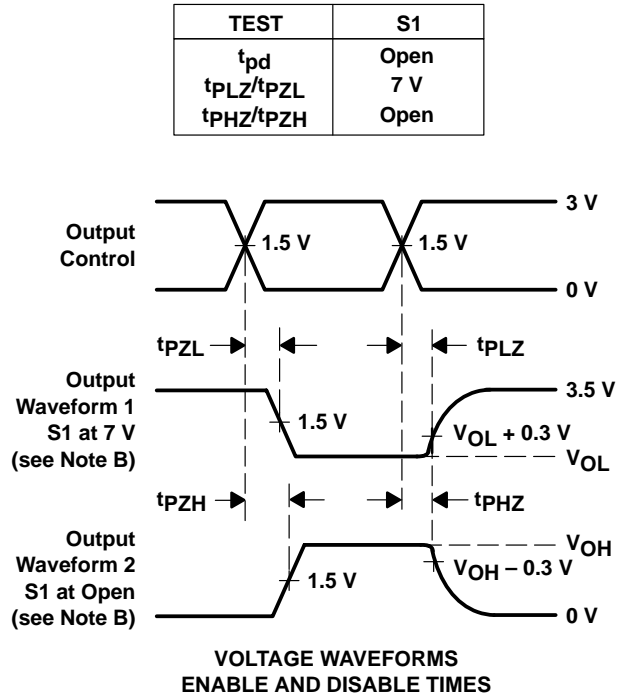
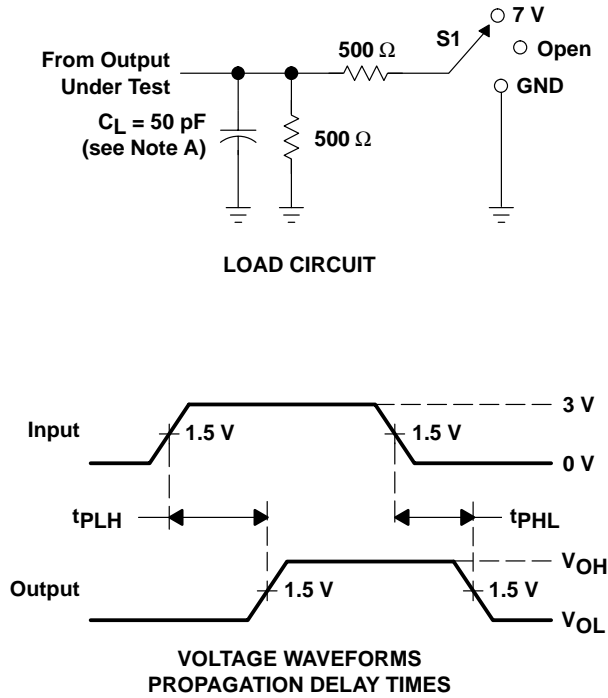
SN74CBTD16211

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SCDS048H – MARCH 1998 – REVISED JULY 2002

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

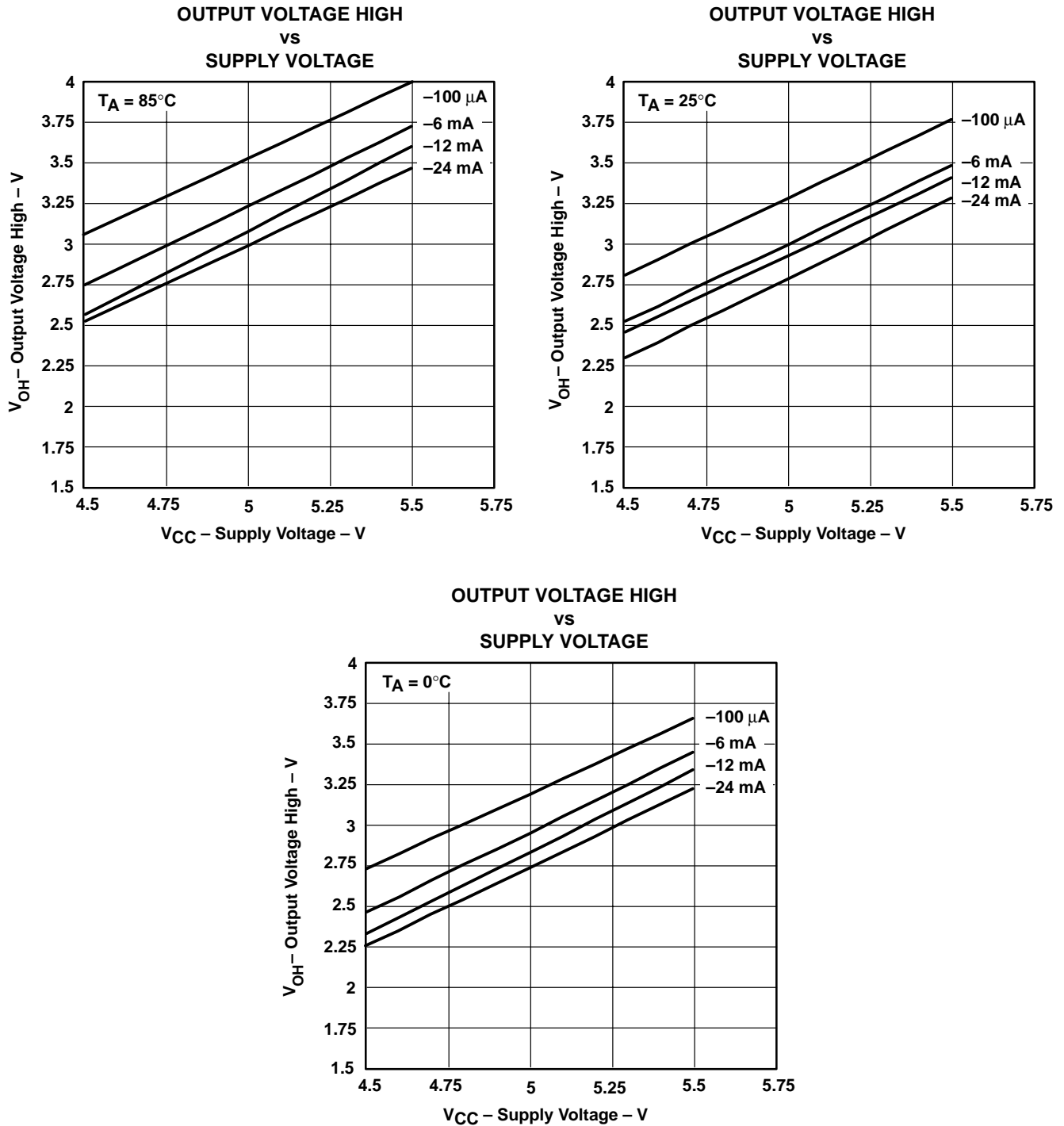


Figure 2. V_{OH} Values

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74CBTD16211DGGR	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74CBTD16211DGVR	ACTIVE	TVSOP	DGV	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74CBTD16211DL	ACTIVE	SSOP	DL	56	20	None	CU NIPDAU	Level-1-235C-UNLIM
SN74CBTD16211DLR	ACTIVE	SSOP	DL	56	1000	None	CU NIPDAU	Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

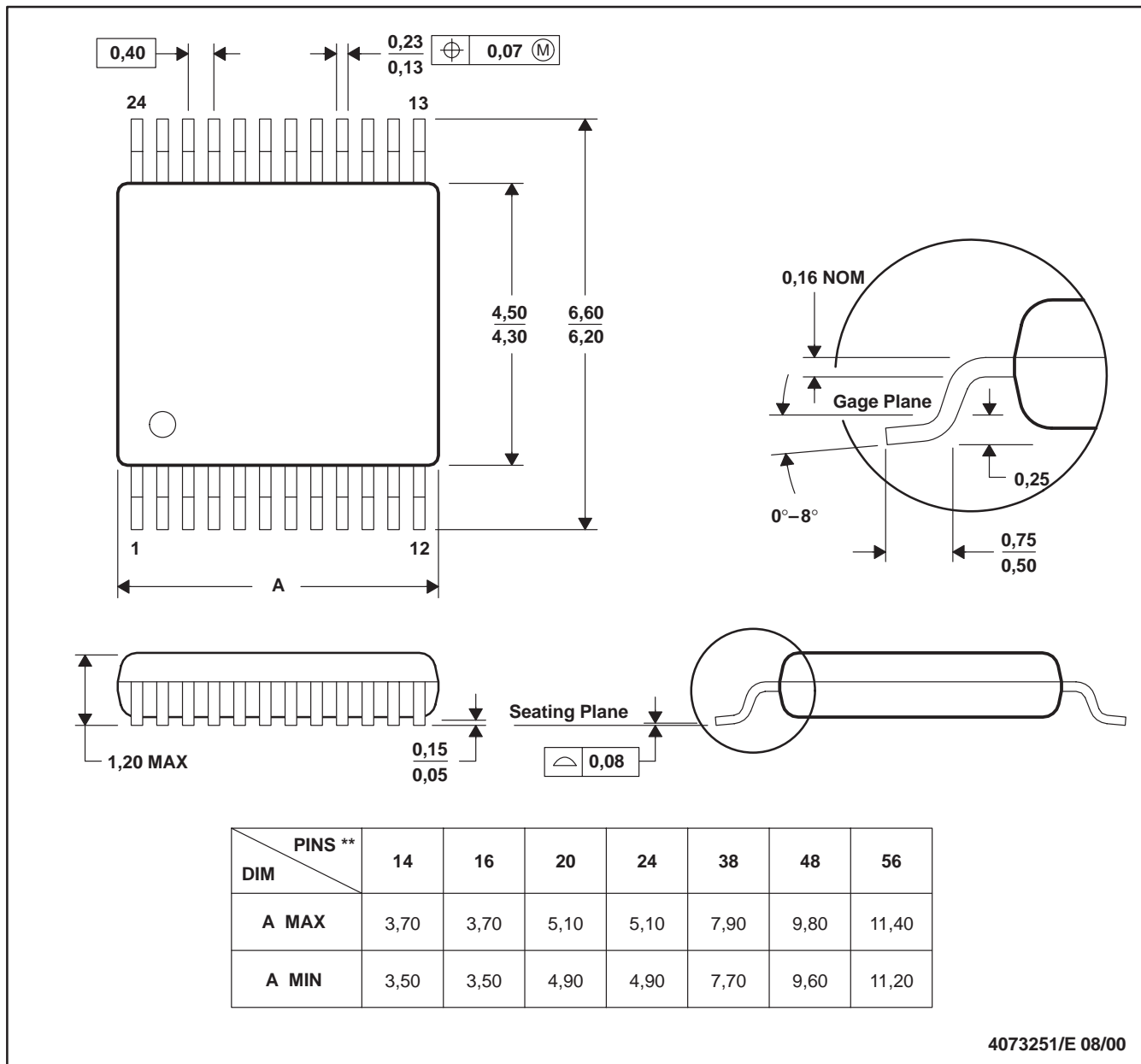
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DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



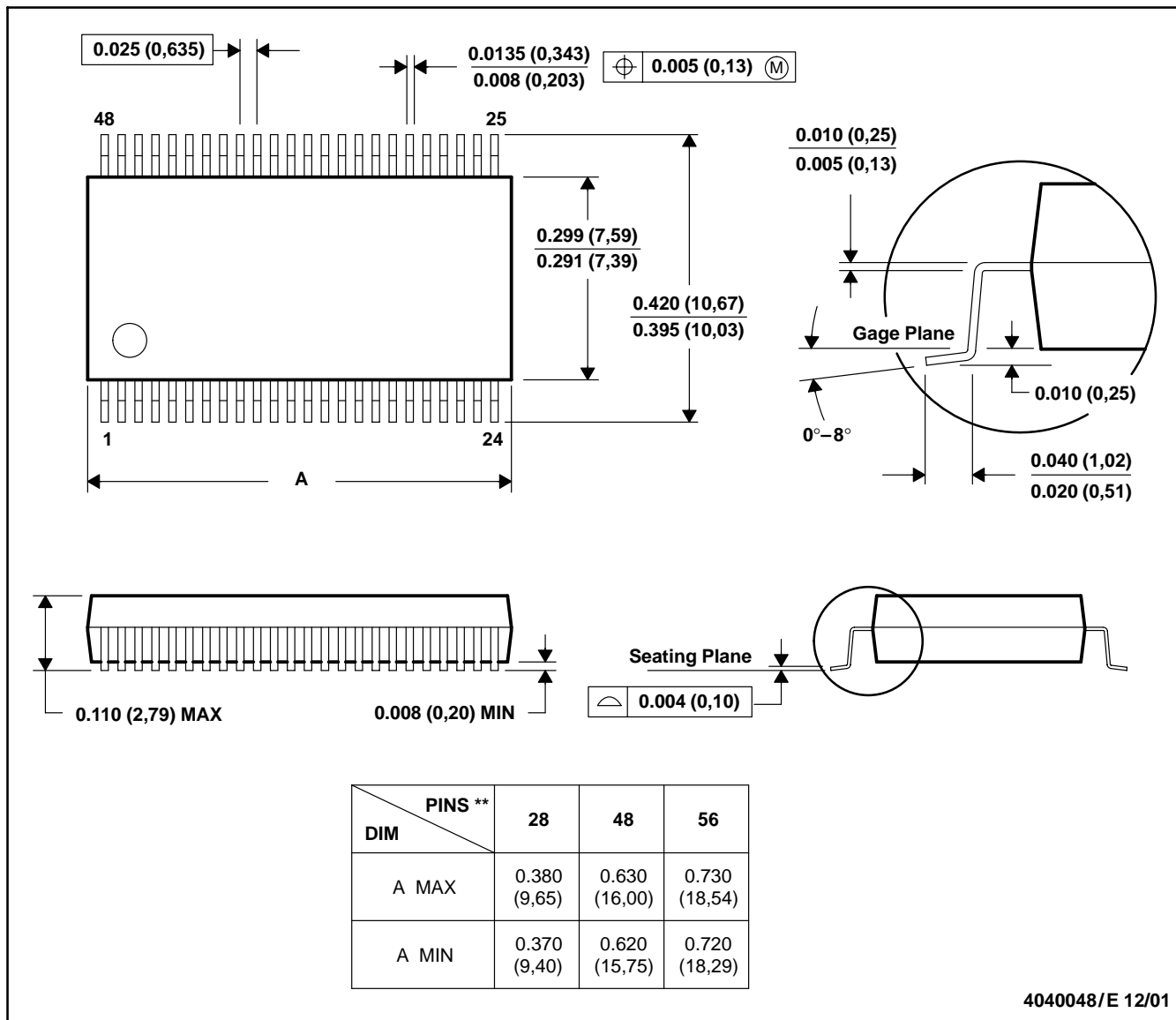
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- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

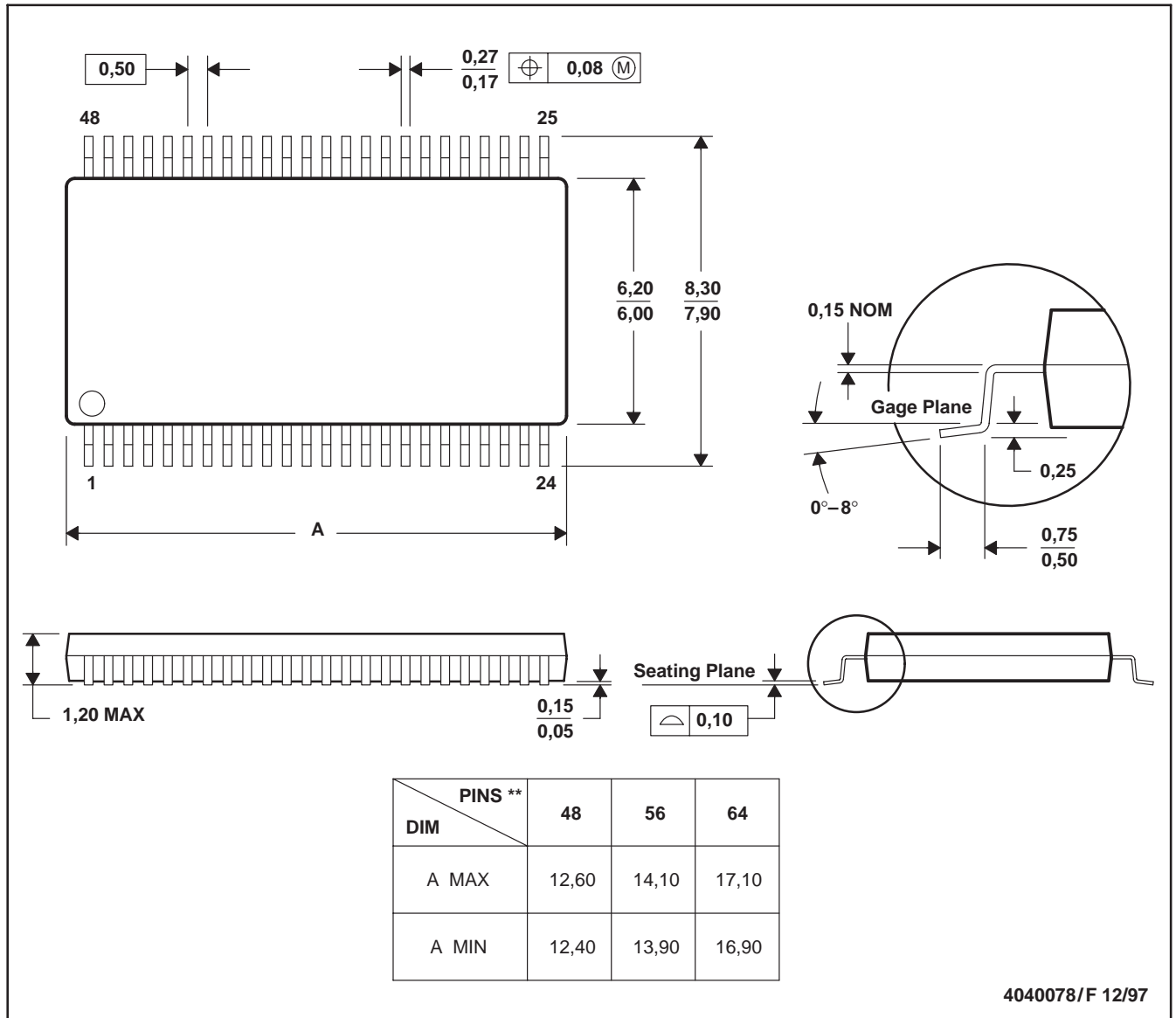


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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